



ATLAS Tile Calorimeter Electronics and Future Upgrades

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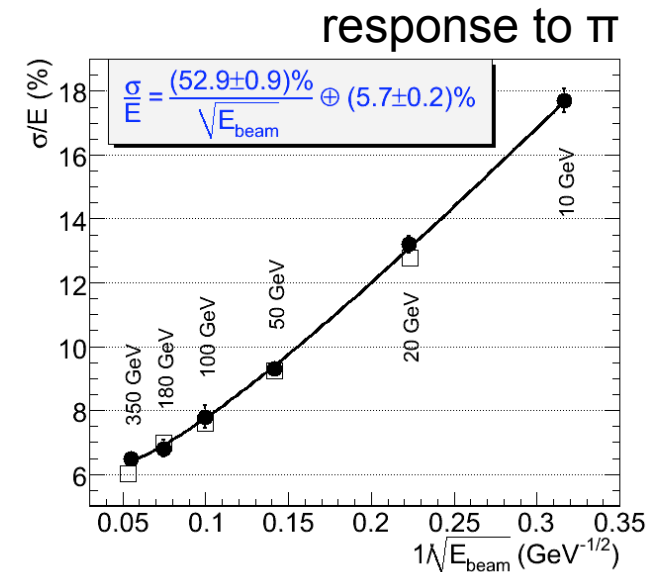
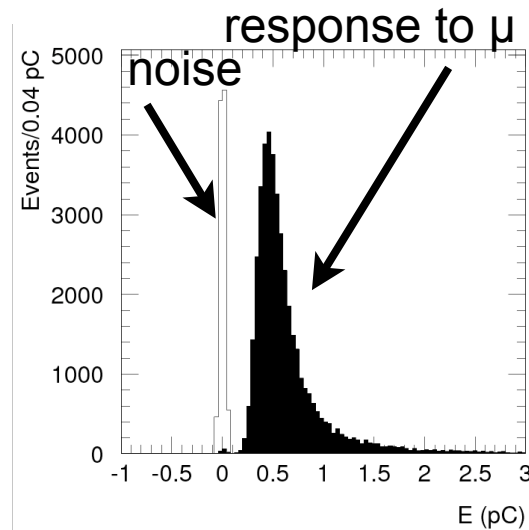
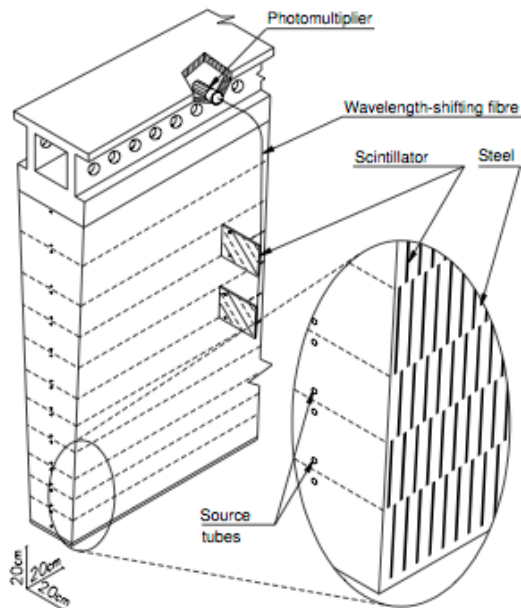
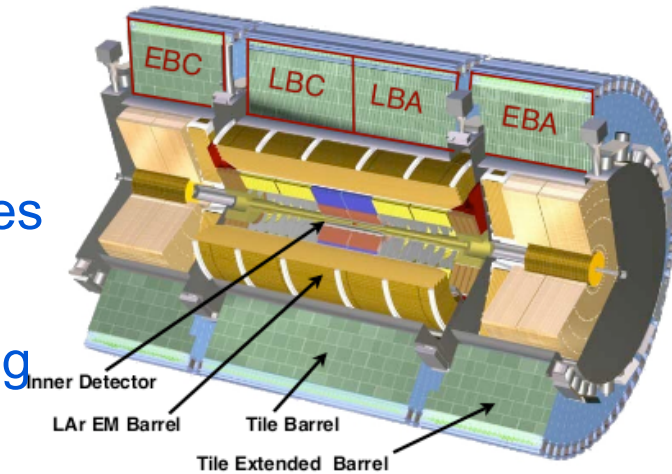
(on behalf of the ATLAS Tile Calorimeter system)



The ATLAS Tile Calorimeter

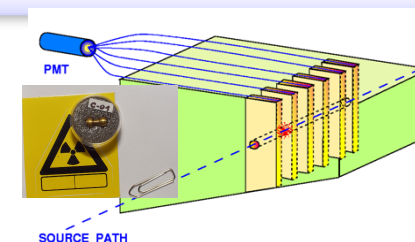


- is the central hadronic calorimeter made of plastic scintillator tiles and steel. Measures hadrons and jet energy and direction
- the scintillators are read out on opposite sides by two PMTs using WLS fibres
- PMTs and FE electronics mounted in 3m long drawers (Super-drawers) at the outer radius





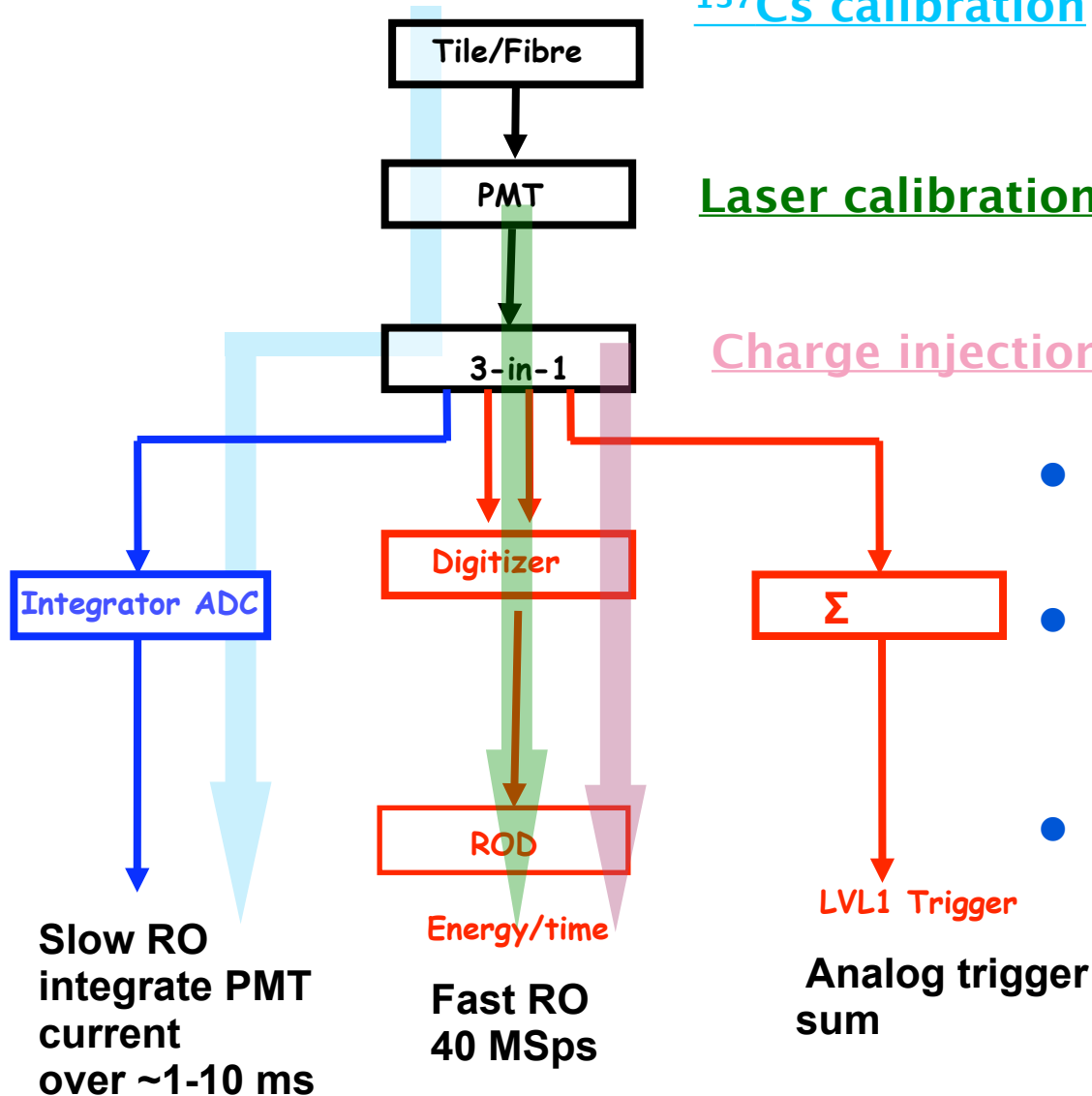
Read-out and calibration concepts



^{137}Cs calibration

Laser calibration

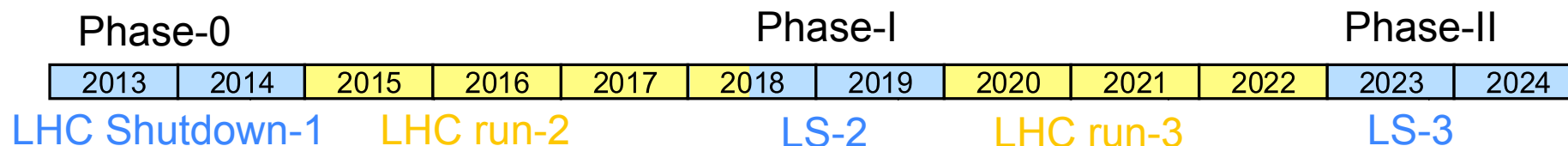
Charge injection calibration



- Analog trigger sum for LVL1 trigger
- digital readout, 16 bit dynamic range obtained using a bi-gain chain with 10 bit ADCs
- DC integrator read-out for calibration and Luminosity Monitor



Tile Calorimeter upgrades timeline



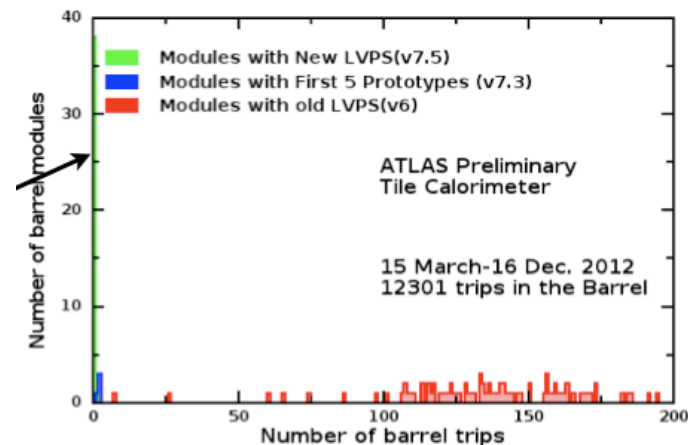
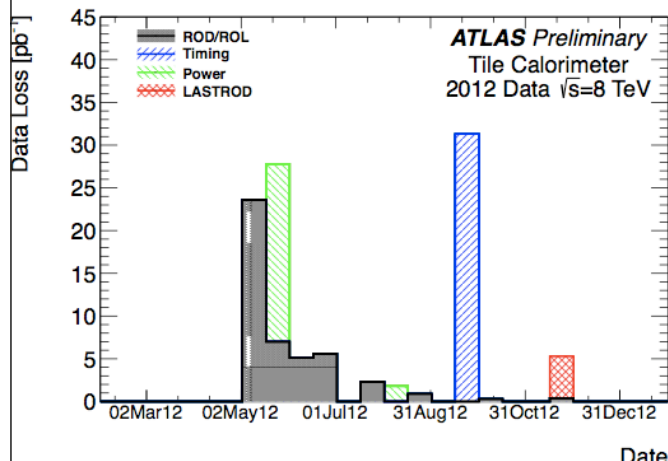
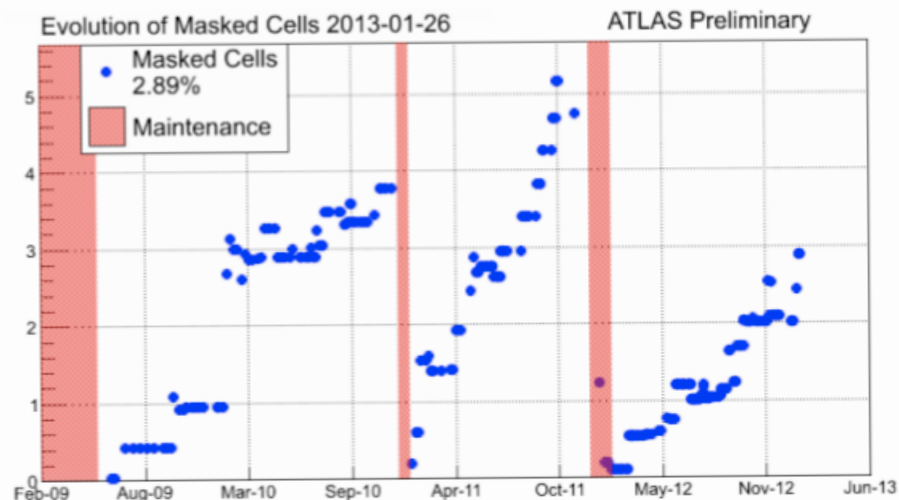
- Run-1 (2009-2012): redesign LVPS on test 40 units
- Phase-0 (2013-2014): install the new LVPS, new MBTS, maintenance of FE boards, Tile 3rd layer in the Muon Trigger logic in $1.3 < |\eta| < 1.5$
- Phase-I (2019): replacement of gap scintillators
- Phase-II (2023): complete upgrade of the FE and BE electronics
 - discussed in this talk



Operation & experience during run-1



- permanent failures in the read-out:
 - PS and power distribution
 - severe errors in data/signal transmission
- temporary failures:
 - 15k PS trip
 - loss of configurations
- Data taking inefficiency: contribute ~9% to ATLAS inefficiency



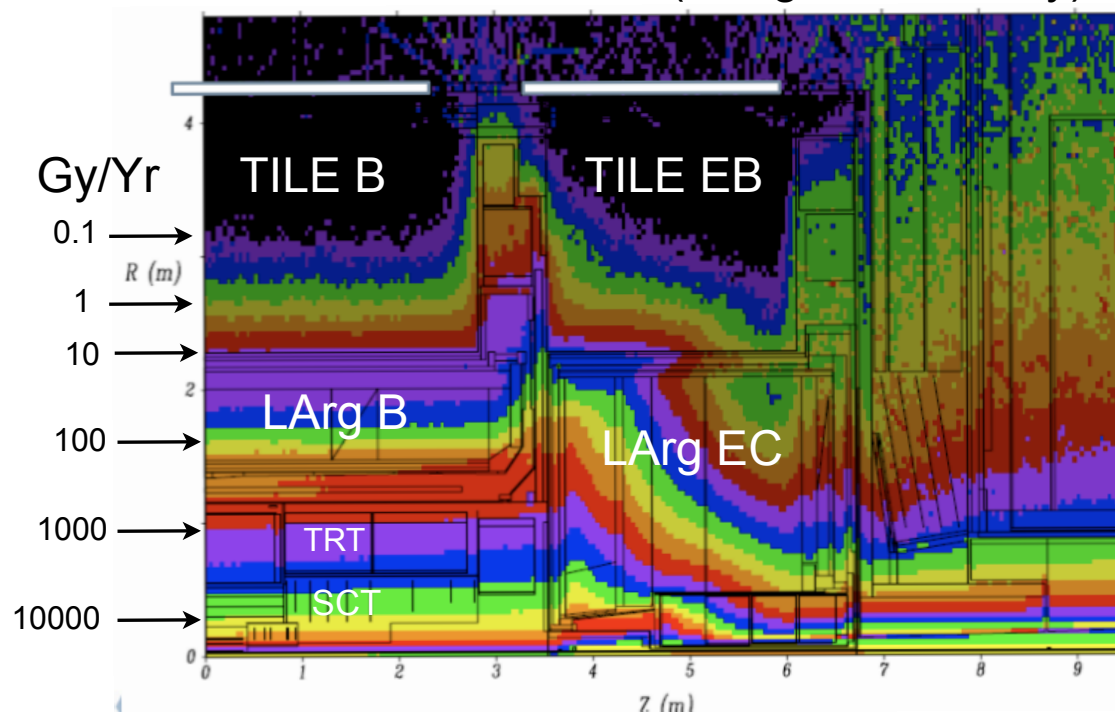


Motivations for the Tile upgrade



- LHC upgrade in 2023 aim for a luminosity of $(5-10) \cdot 10^{34} \text{ cm}^{-2}\text{s}^{-1}$
 - better radiation tolerance is desirable
 - increased interaction rate demands for a better precision and finer granularity in the trigger
- ageing of components
 - exceeding the design lifetime
- improve the reliability
 - reduce/simplify the maintenance needs
- improve the accessibility
 - ALARA considerations

TID simulation (design Luminosity)



Phase 2 Radiation Tolerance Requirements (Estimate), <u>TileCal HV Opto</u>					
Type	Simulated Dose/Yr	Simulation Safety Factor	Low Dose Rate Safety Factor	Lot Variation Safety Factor	Total 10 Year Operation
TID	8.13E-01 Gy/yr	1.5	5	4	2.44E+02 Gy
NIEL	7.62E+10 n/cm ² /yr	2	1	4	6.10E+12 n/cm ²
SEE	1.85E+10 p/cm ² /yr	2	1	4	1.47E+12 p/cm ²

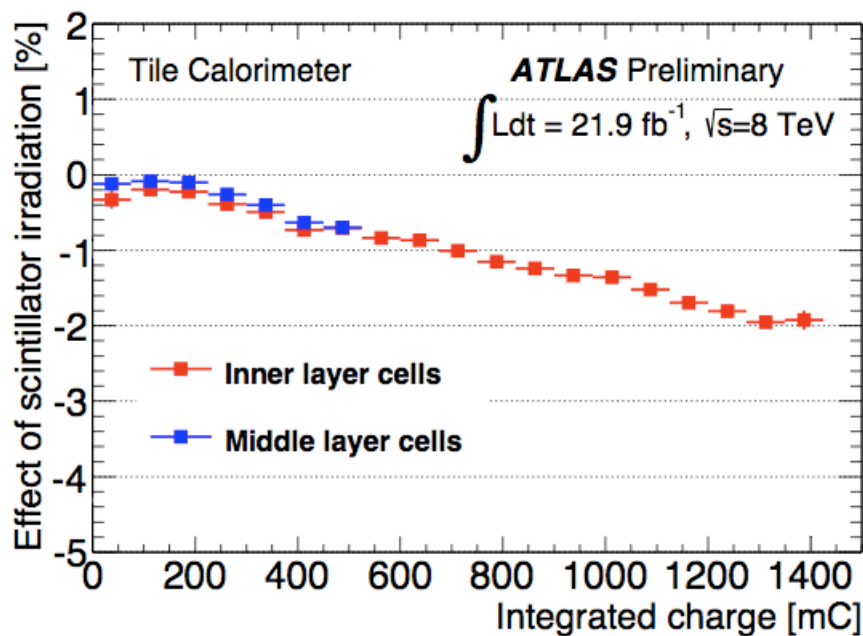
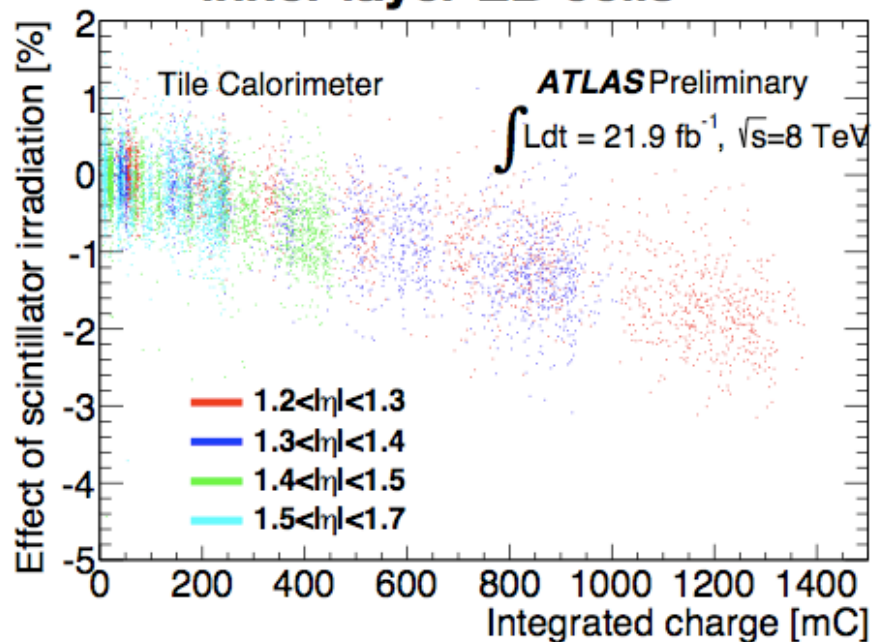


Irradiation effects on scintillator



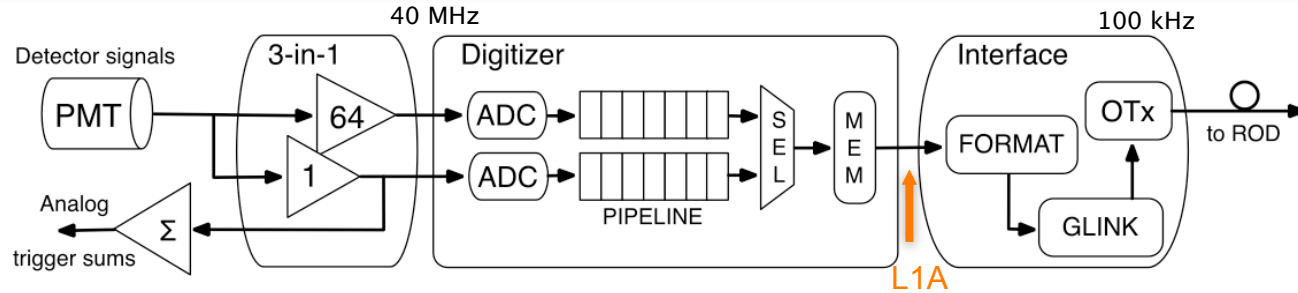
- difference between the Cs (Minimum Bias) and Laser response is interpreted as the effect of the irradiation on the scintillator: $\leq 2\%$ for the worst case cells
- Cell light budget is fairly large (~ 70 phe/GeV), a factor X2 loss is expected not to be critical. Detailed study ongoing

inner layer EB cells



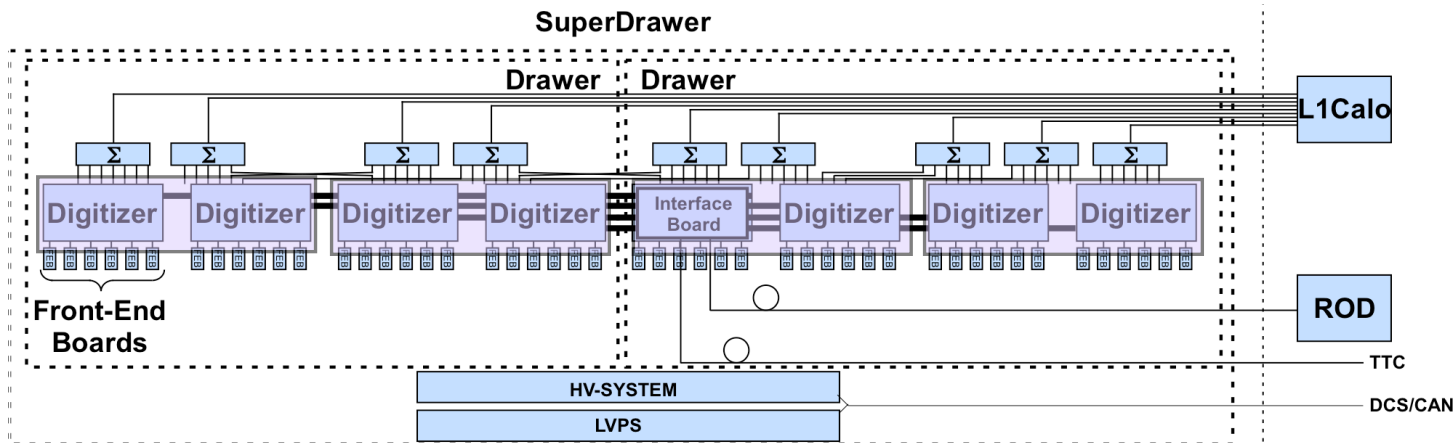


Present read-out system



- 3-in-1 FE board: shaping, amplification, integration
- Mother board: programming and powering of FE boards
 - int ADC, TTCrx, trigger summing boards, CANbus
- Digitizer cards: TTCrx, Digitization at 40MSps, pipelines
- Interface card: Otx to the ROD, TTC Orx

Total data rate	~165 Gb/s
Number of links	256 (+256)
Data rate per link	640 Mb/s
Links per super-drawer	1 (+1)

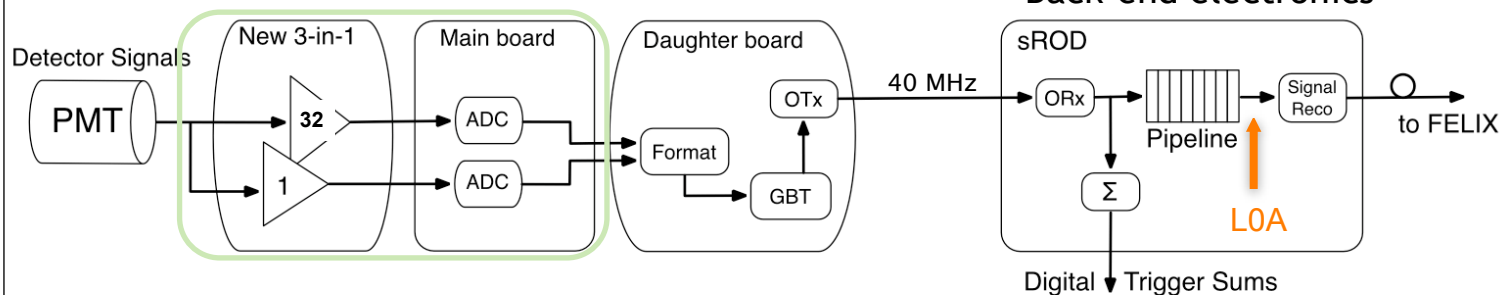




Future read-out system

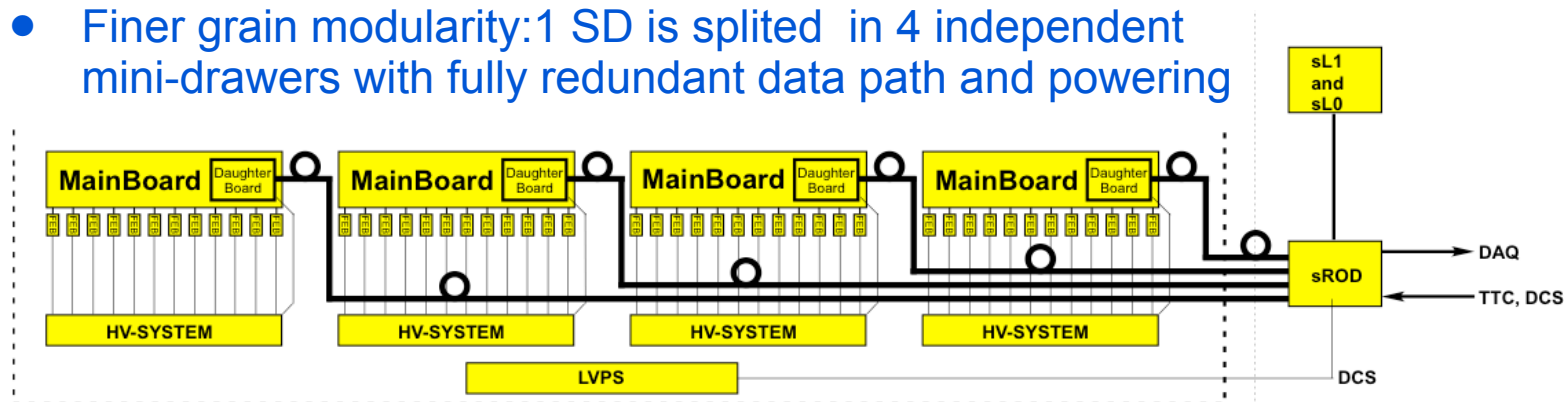


Option 0



- Simplification: reduced no. of boards and less inter-connections
- Daughter board: high speed optical communication for transmission of full data at 40 Mbps to the sROD in USA15
- Pipelines and de-randomizers in the sROD, control and monitor. Digital information for the LVL0/LVL1 Trigger system
- Finer grain modularity: 1 SD is splitted in 4 independent mini-drawers with fully redundant data path and powering

Total data rate	~80 Tb/s
Number of links	4096 (+4096)
Data rate per link	10 Gb/s
Links per Duper-Drawer	4x4 (+4x4)
Data rate per SD	160 (+160) Gb/s

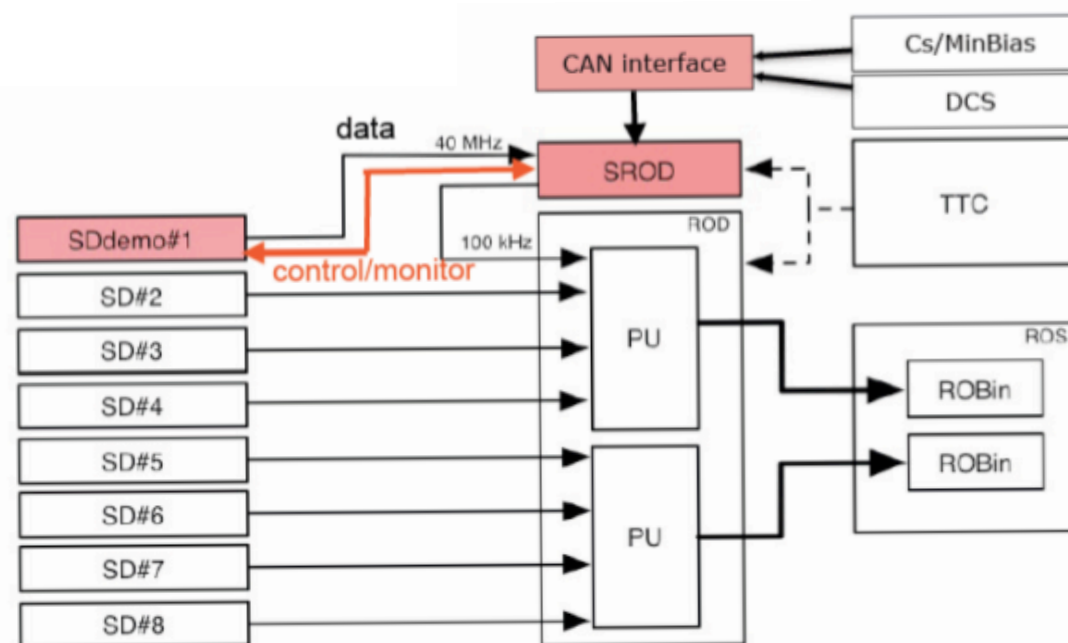
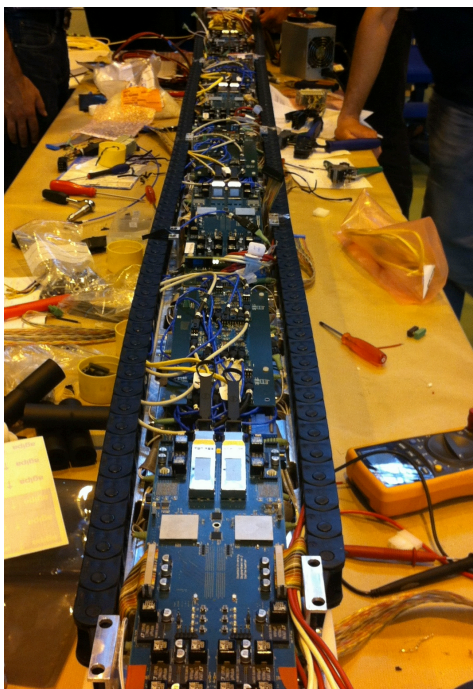




The demonstrator project



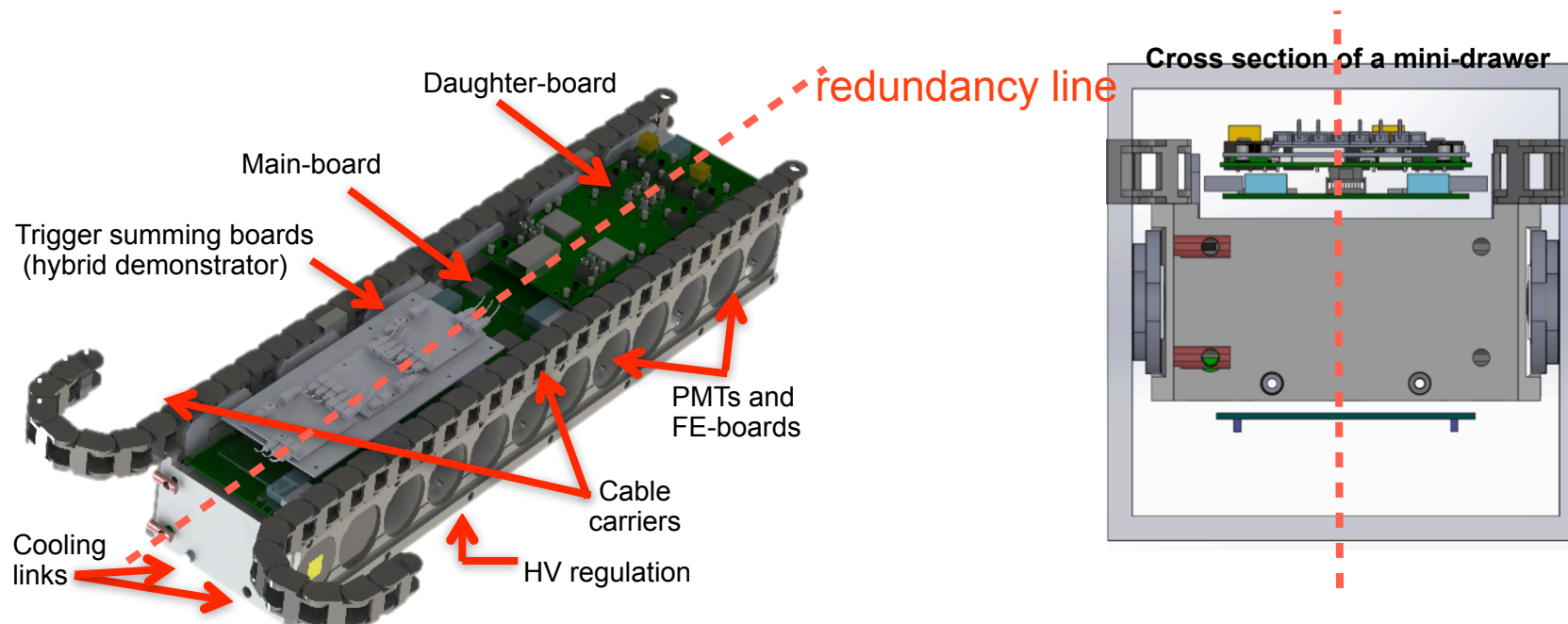
- Hybrid slice of the future system to be integrated asap in the current detector to evaluate the design/technology.
 - As **similar as possible to the phase-II system** but maintaining full compatibility with the current system.
 - receive TTC/CANbus commands from sROD
 - send data to the ROD through the sROD
 - provide both analog and digital trigger output





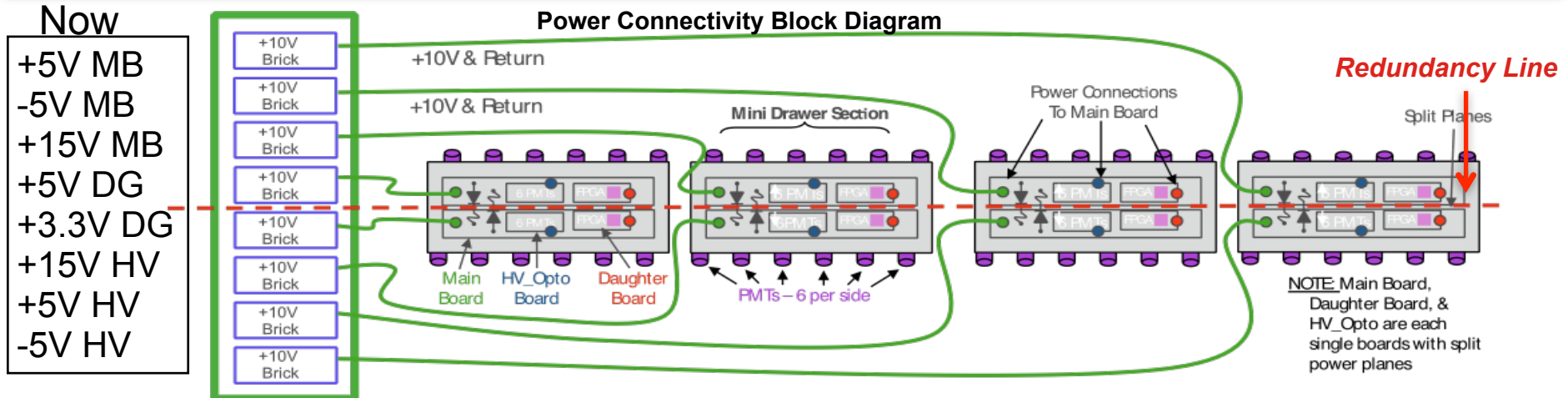
Mini-drawers

- The Super-drawer will be split further to simplify the handling and allow access in partial detector opening
- 4 independent mini-drawers, each one with 2 independent read-out sections:
 - 12 PMTs and FE boards reading out 6 cells. (3-in-1 or other 2 future options)
 - 1 main-board: for the corresponding FEB option
 - 1 daughter-board: single design
 - 1 HV regulation board: HVOpto or HVRem options
 - 1 adder base board + 3 adder cards: only for hybrid demonstrator

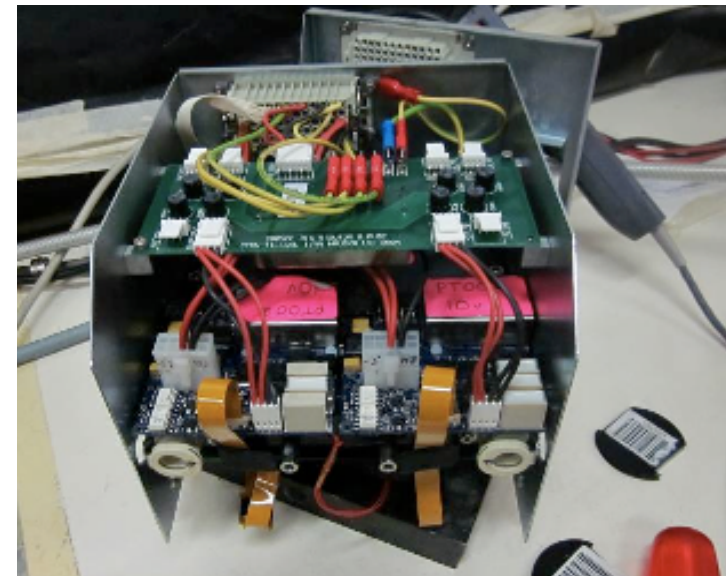




Low Voltage Power Distribution



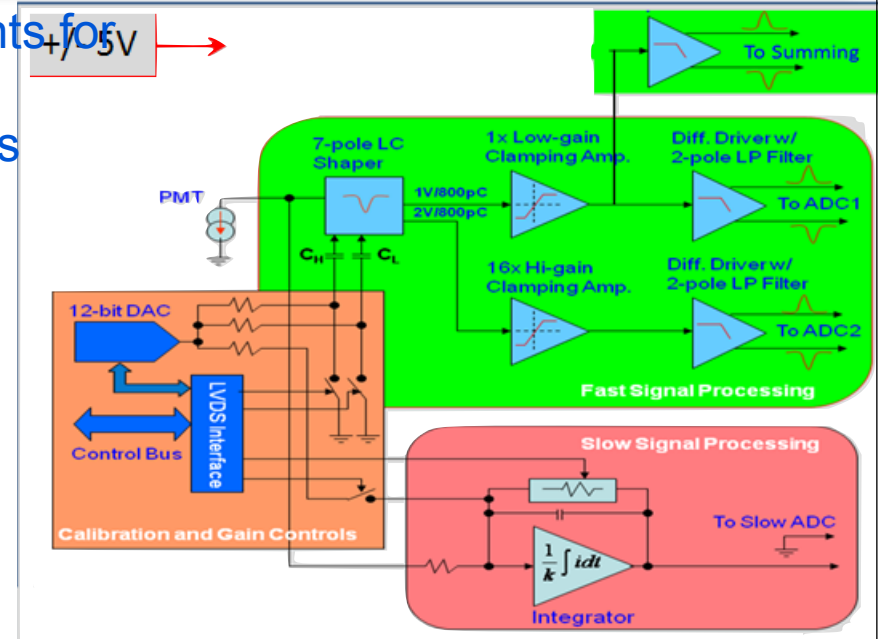
- three-stage power distribution system
- bulk 200VDC PS in USA15
- “finger LVPS”: custom evolution of the used DC/DC converter
 - 8 separate units providing only +10V
 - Each unit powers half of a mini-drawer but can power both for redundancy (diode OR)
 - first unit fully operational
- Point-of-load regulators
 - mounted on Main Board, Daughter Board and HV Opto
 - Completed TID tests on 5 COTS regulators, marginal results for -5V regulator
 - NIEL and SEU tests to be done in December 2014



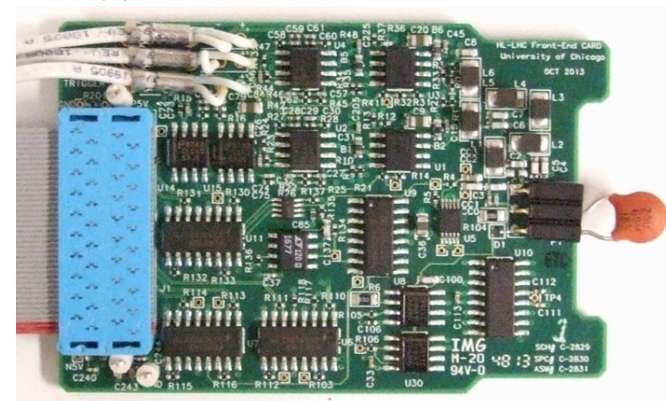
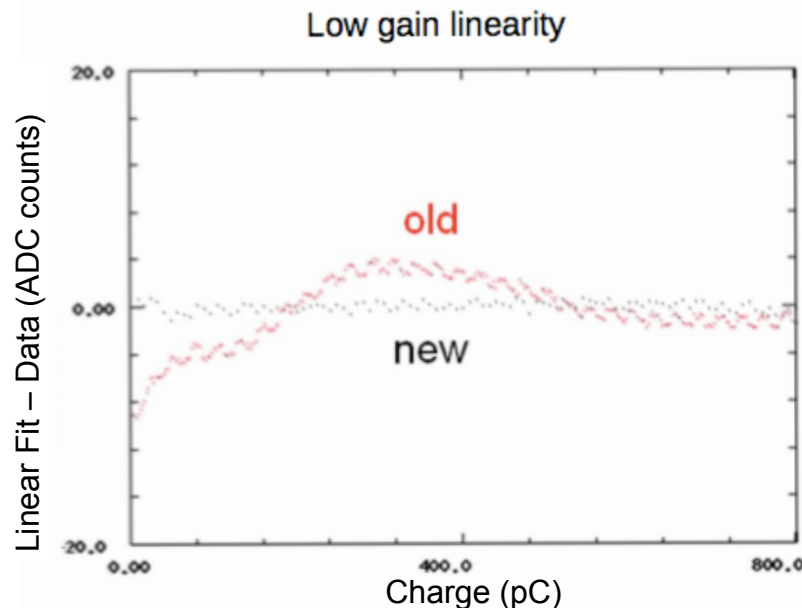


3-in-1 FE board

- Based on current FE. Only analog components for shaping and integration:
 - High/Low gain and trigger analog outputs
 - Charge injection calibration
 - Integrator read-out
- higher radiation tolerance
- improved noise performance
- improved linearity performance
- prod.version manufactured and qualified.



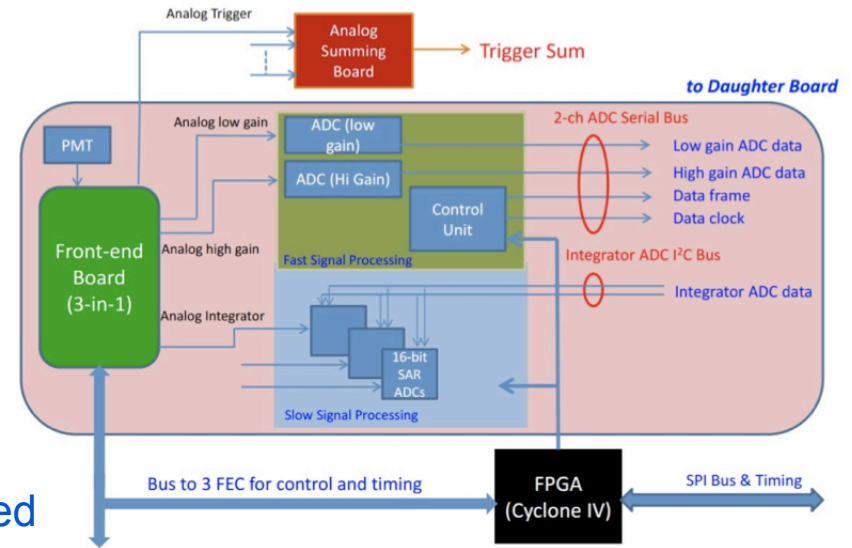
Used in the hybrid demonstrator, since provides analog output to the LVL1 trigger



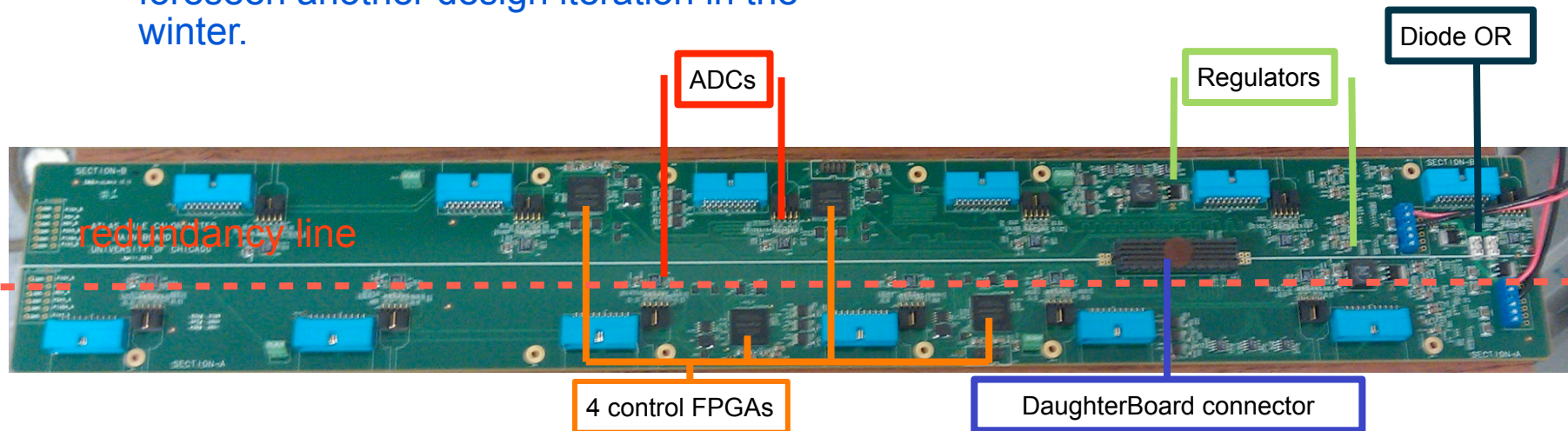


Main-board for new 3-in-1 FEBs

- Made of two completely independent sides. Power included.
- Local voltage regulator ($\pm 5V$, $+2.5V$, $1.2V$),
- FPGA for clock distribution control and monitoring of 12 FEBs (6 on each side)
- ADCs for HG/LG and integrator FEB outputs
- LVDS communication to the daughterboard at 560 MHz
- Status:
 - version 3 manufactured and validated. Used in the first demonstrator prototype. We foreseen another design iteration in the winter.



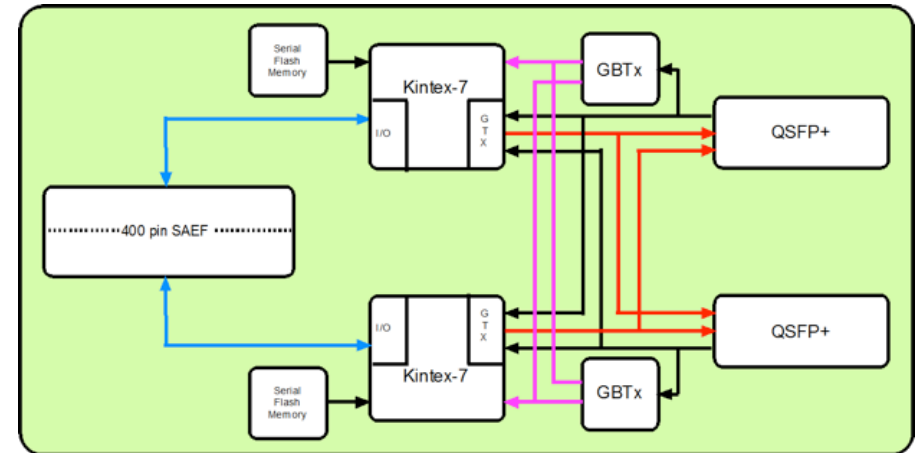
High Radiation - Patch Panel End



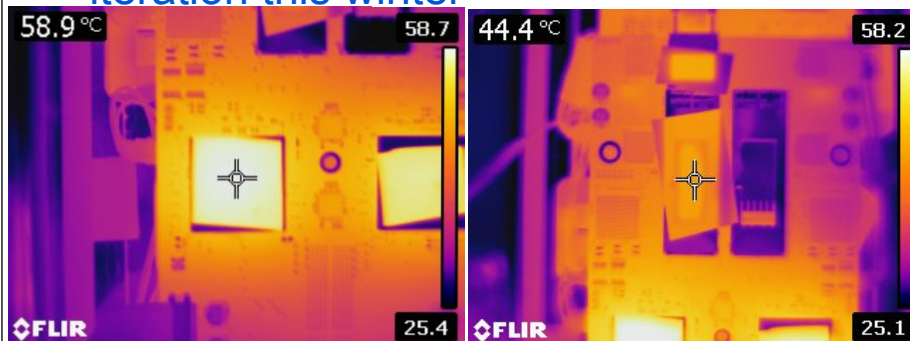


Daughter-board

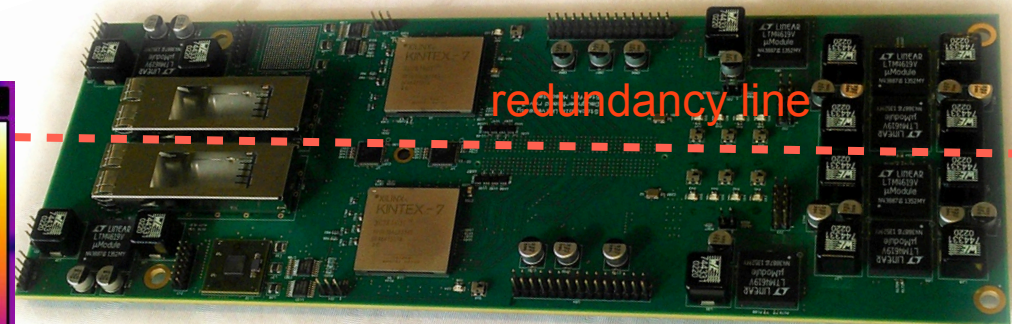
- provides high speed communication with the back-end electronics
 - collects format and transmits the read out and DCS data.
 - receives and routes commands and configurations from ROD and DCS
 - two completely independent sides with Kintex-7 FPGA, QSFP, GBTx
 - uses triple redundant FPGA programming, scrubbing and partial reconfiguration
 - Firmware can be uploaded through the optical link
- Status: Produced 4+4 units of the third version. We foreseen a further design iteration this winter



Conceptual design of daughter-board (third prototype)



Infra-red images showing two programmed FPGAs and one QSFP

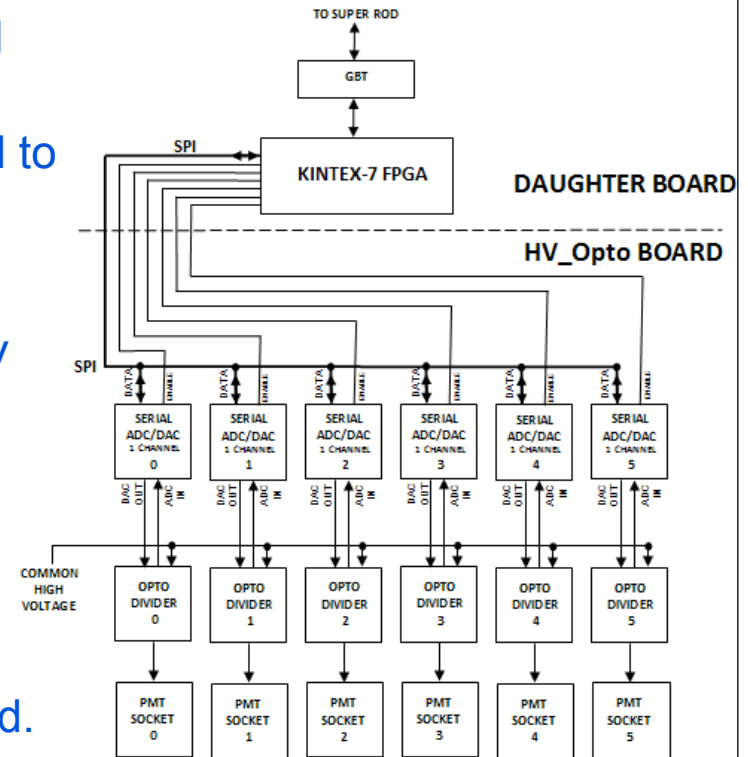


daughter-board (third prototype)

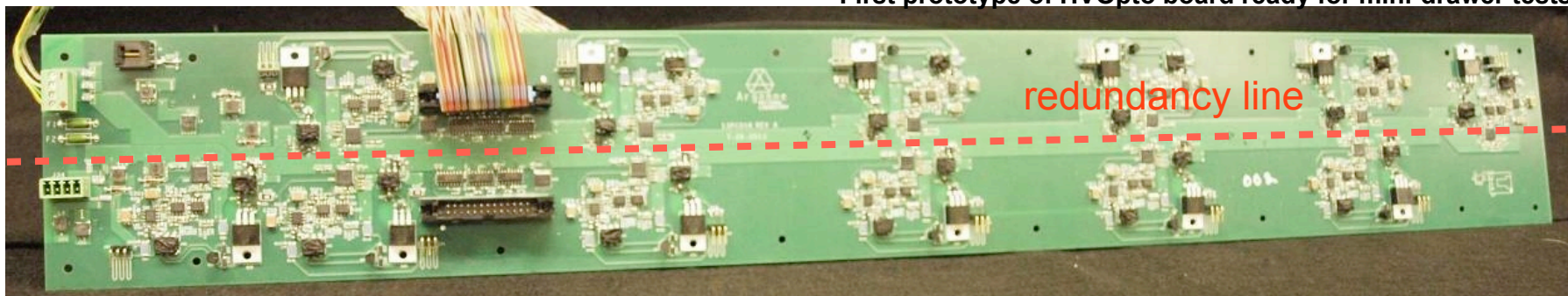


High voltage regulation & distribution

- two options under investigation: remote (HVRem) and local HV regulation (HVOpto)
- HVRem: the existing local regulation system is moved to USA15 and individual cables are routed to the PMTs. First prototype built, under testing.
- HVOpto: largely based on the existing system use Kintex-7 FPGA in the daughter board for control of HV settings and monitoring
 - Introduce possibility of switching on/off individual PMTs
 - First 4 boards tested and performance meets specifications
 - First TID, NIEL, SEU tests show no hard failures. Sensitivity in some components being investigated. Mitigation of the observed SEU seems viable.



First prototype of HVOpto board ready for mini-drawer tests

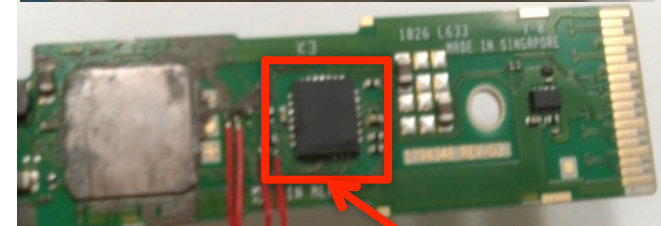
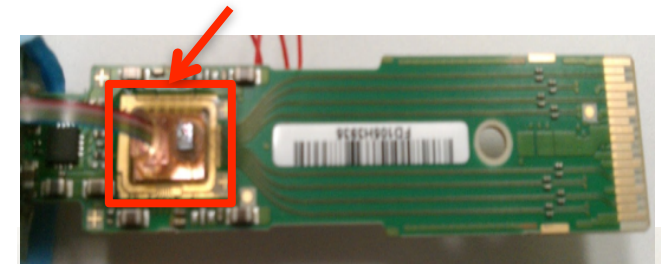




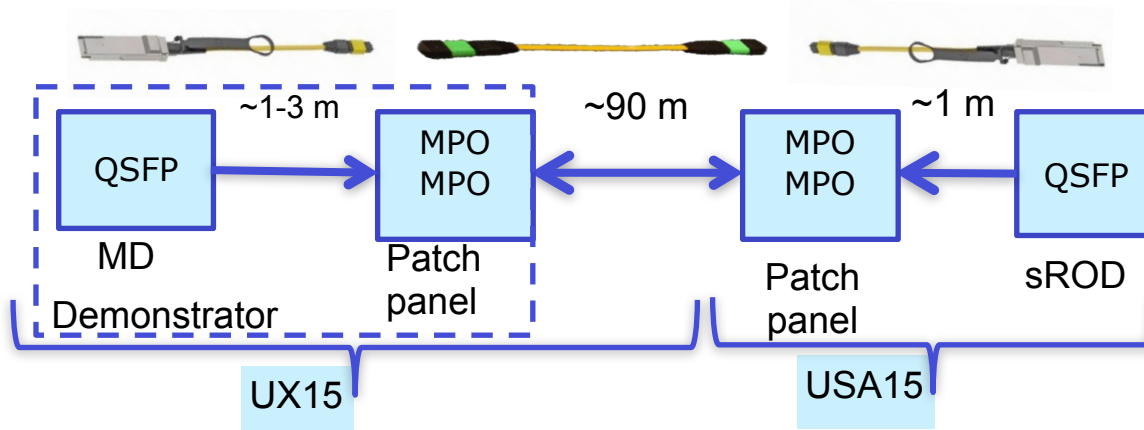
Read-out links

- 8 read-out links/super-drawer: 1+1 (redundancy) x 4 mini-drawers
- Luxtera Active Optical links:
 - 4 bi-directional channels: 1-14 Gbps/ch
 - excellent error rate: BER 10^{-18} (~1err/3y)
- Made out of 130 nm Silicon On Insulator CMOS
- TID: tested up to 165 kRad passed but the PIC (used for configuration) fails at ~20 kRad. Replacement with an FPGA under investigation.
- SEU: tested under fluence of 1.2×10^{12} p/cm² operating at 10Gbps show ~0 Tx errors, few Rx errors. Still under investigation.

Modulator

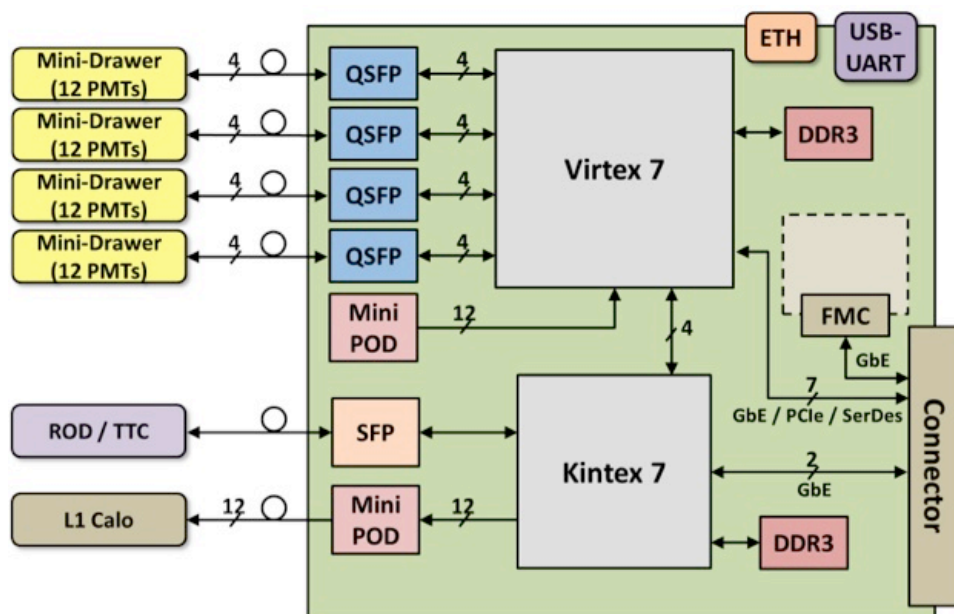


PIC Microcontroller

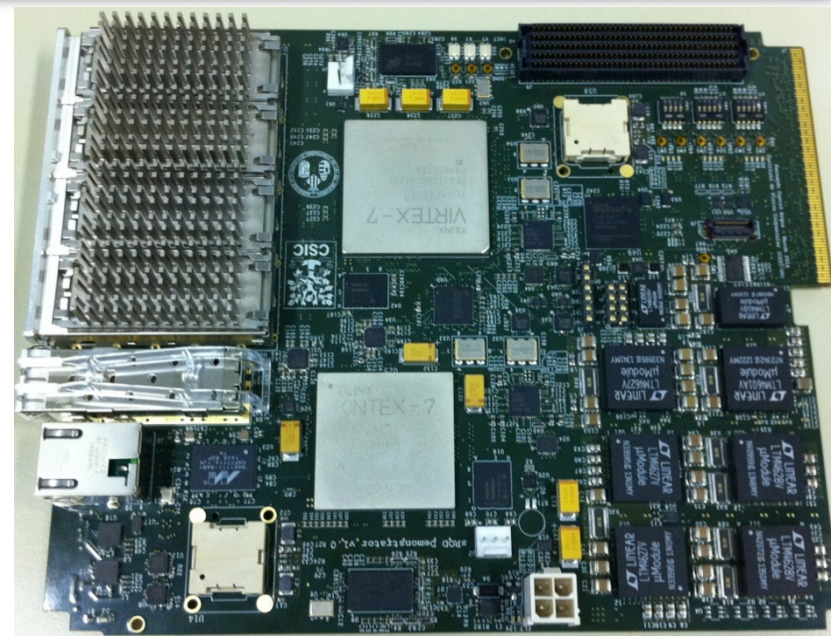




Super-ROD demonstrator prototype



Conceptual design of super-ROD prototype

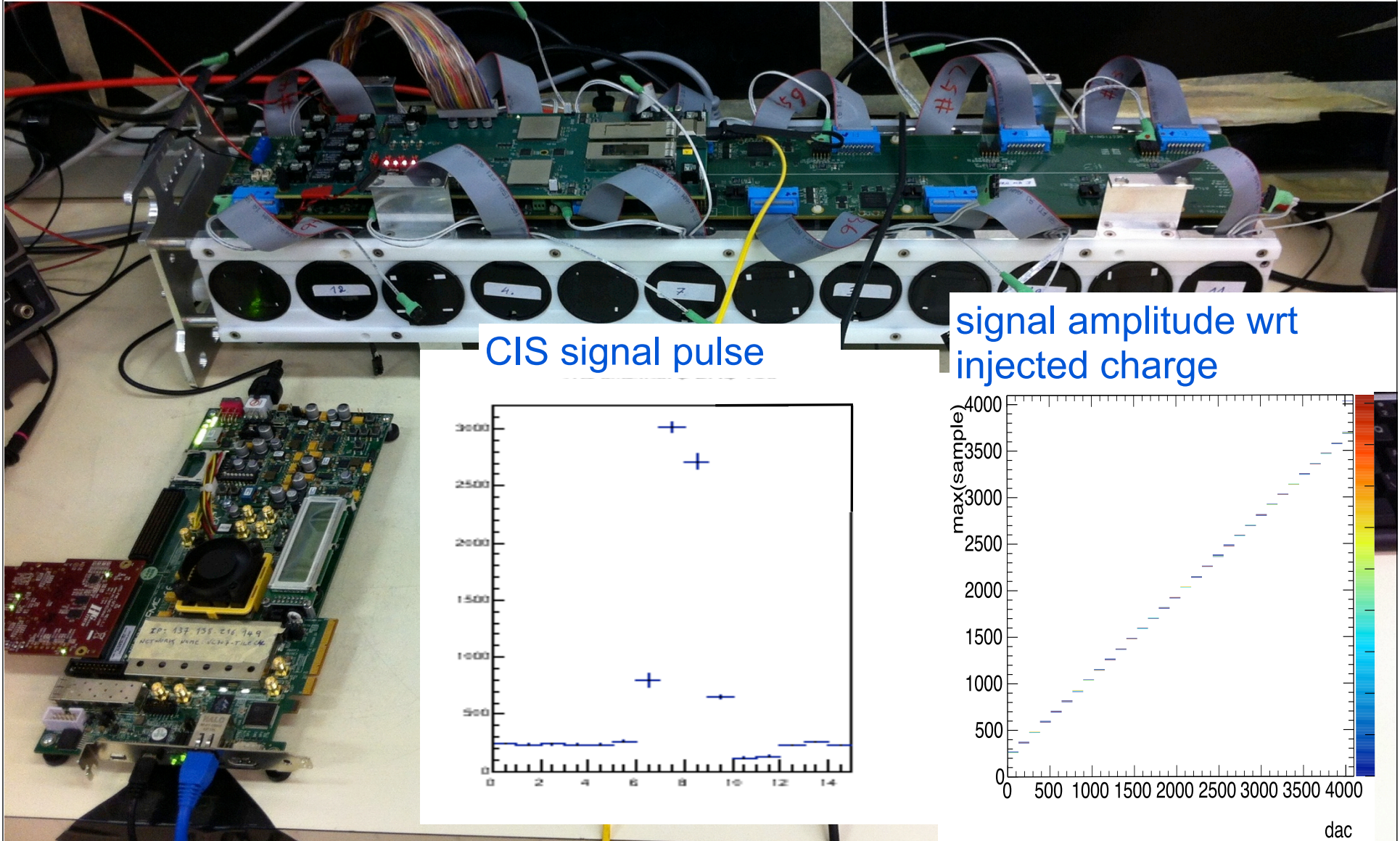


Super-ROD prototype

- Super-ROD interfaces the FE with current ROD and DCS
 - Prototype compliant with midsize AMC (180.6 mm x 148.5 mm)
 - Read-out of a complete super-drawer (4 mini-drawers) with QSFPs
 - Corresponding to 1/8 of input links of the design for phase-II
 - 1 Xilinx Virtex 7 FPGA 48 GTX@10Gb/s for data/DCS input and TTC/DCS output
 - 1 Xilinx Kintex 7 FPGA 28 GTX@10Gb/s to interface current ROD/TTC and L1Calo
 - 512 MB DDR3 SDRAM and 1 Gb flash per FPGA
- Status: first prototype received, testing ongoing.



Test-bench @ CERN





R&D of other FE options



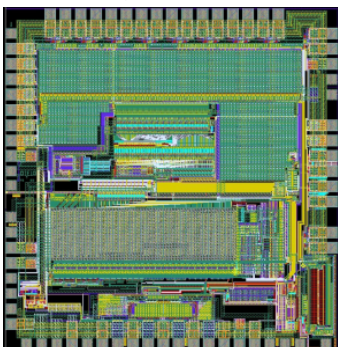
QIE ASIC

- Charge Integrator and Encoder (QIE) chip from Fermilab
- Current splitter with multiple ranges and gated integrator + on-board flash ADC
 - Dead-timeless digitization (No pulse shaping) at 40 MHz operation
 - 17-bit dynamic range in 10 bits
- Status:
 - 40 chips in hand
 - Test of TID completed SEU ongoing.
 - Design review to improve resolution
 - integration in a FEB for 2015

FATALIC

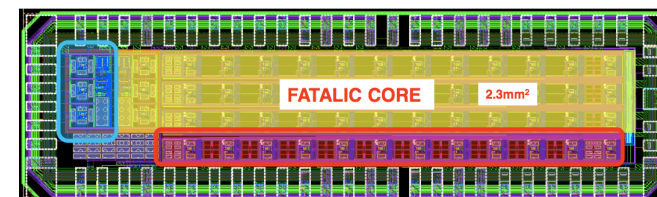
- FATALIC 4 ASIC:
 - Current conveyor
 - Shaping stage with 3 different gain ratios (1, 8, 64)
 - 3 x 12-bit ADCs
 - 40 MHz operation
- Status:
 - received in September, first test ongoing
 - integration into a FEB for 2015

QIE v10.5



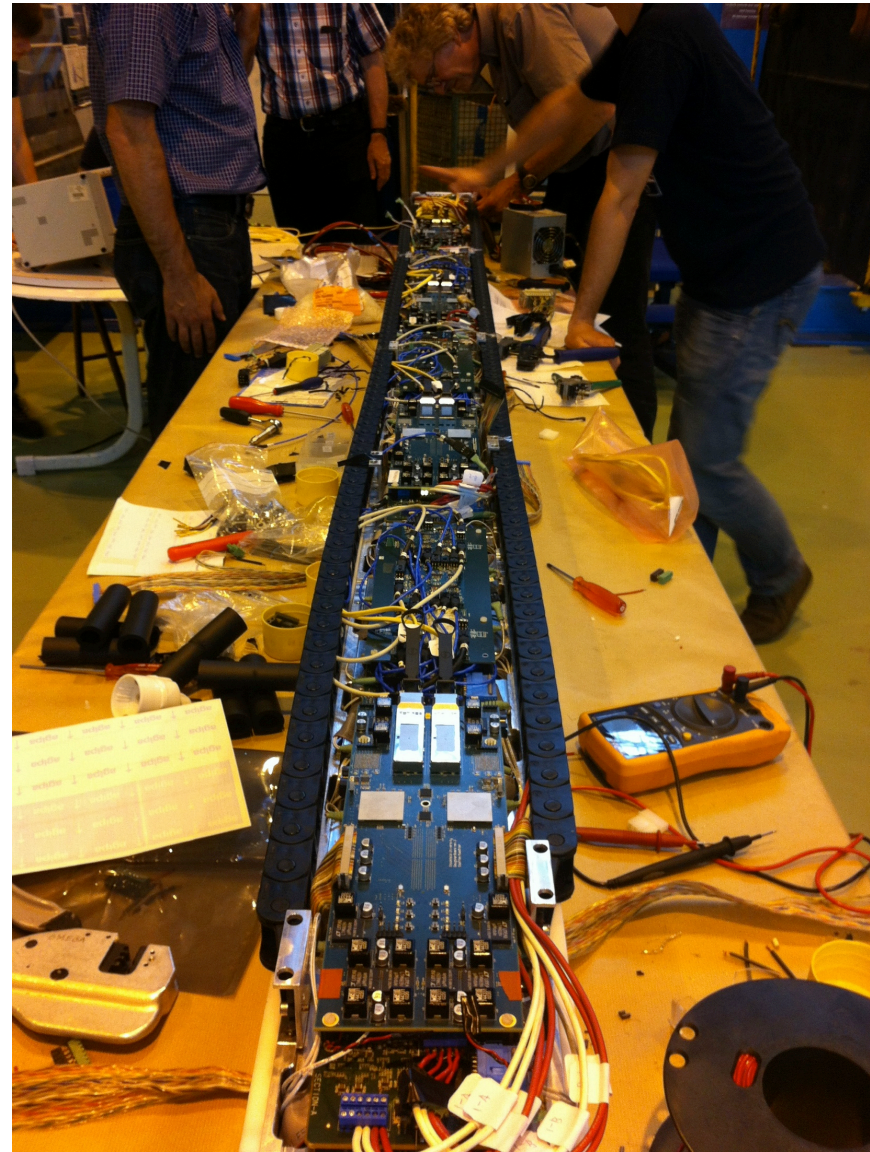
All 3 options will be extensively tested for performances and radiation tolerance

FATALIC-4





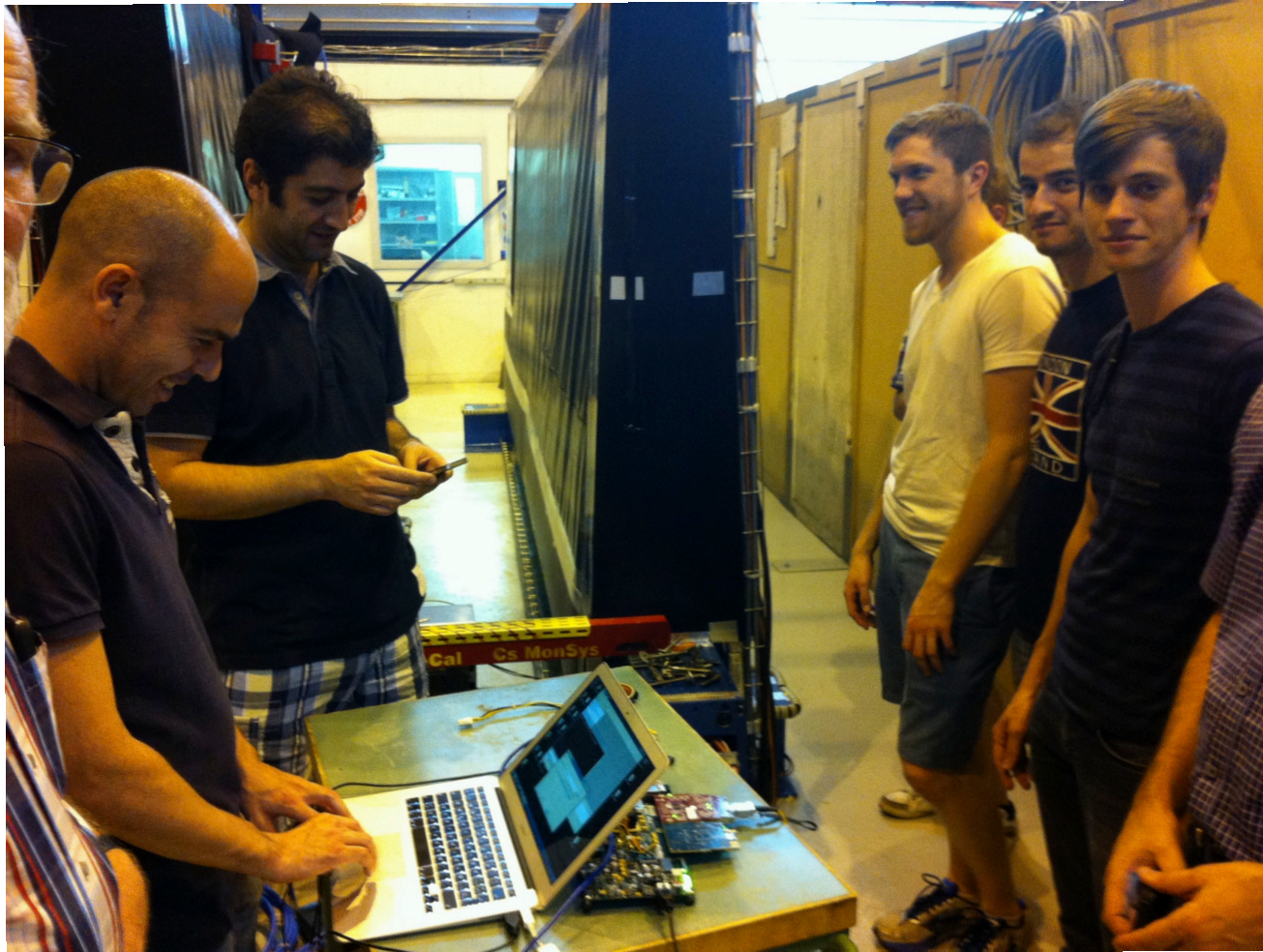
Demonstrator assembly in June 2014



TWEPP - 24th September 2014



Insertion in the spare module and first tests



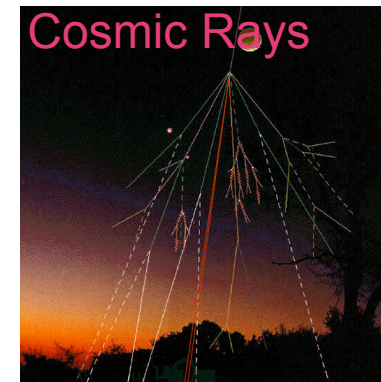
test/calibration using
Cesium source



test/calibration using
Laser



test/calibration using
Cosmic Rays

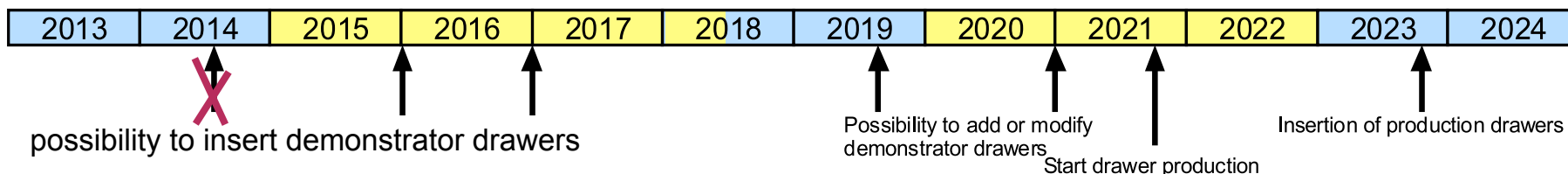




Summary



- The project to upgrade the Tile calorimeter for HL-LHC is moving full steam ahead.
- The overall design is in good shape. Few alternative choices need to be fully evaluated under beam tests and with an early slice integration into ATLAS.
 - The first complete hybrid prototype (SD+sROD) originally target for insertion into ATLAS this year is under extensive testing in the LAB
 - additional mini-drawer prototypes with the different front-end options are expected to join the testing in 2015
- A beam test campaign is starting, targeting Summer 2015 and 2016.





Backup



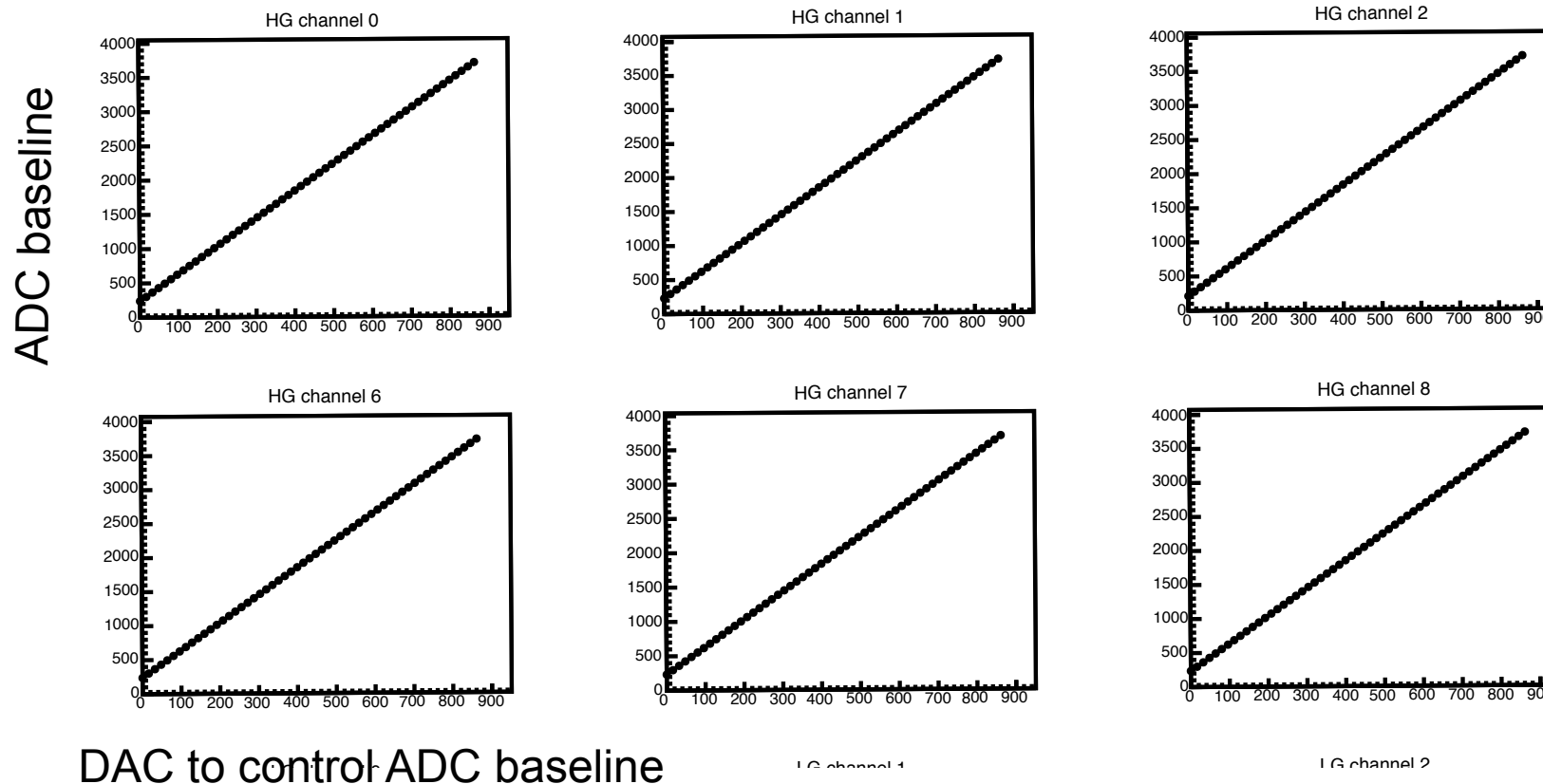
Basic operation tests

linearity of ADC baseline settings



- simple operations of FADC read-out to test the alignment

A. Valero

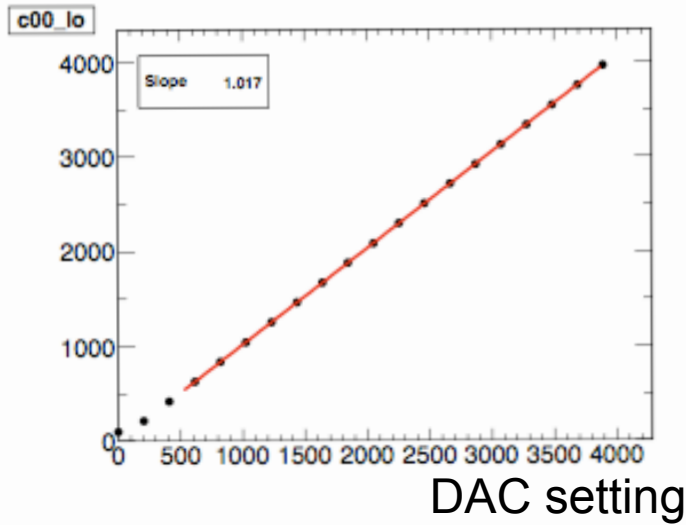




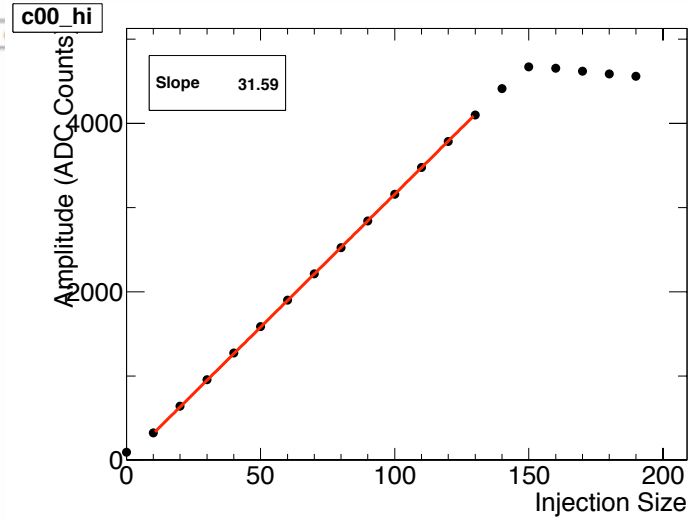
Basic operation tests first look at calibration constant



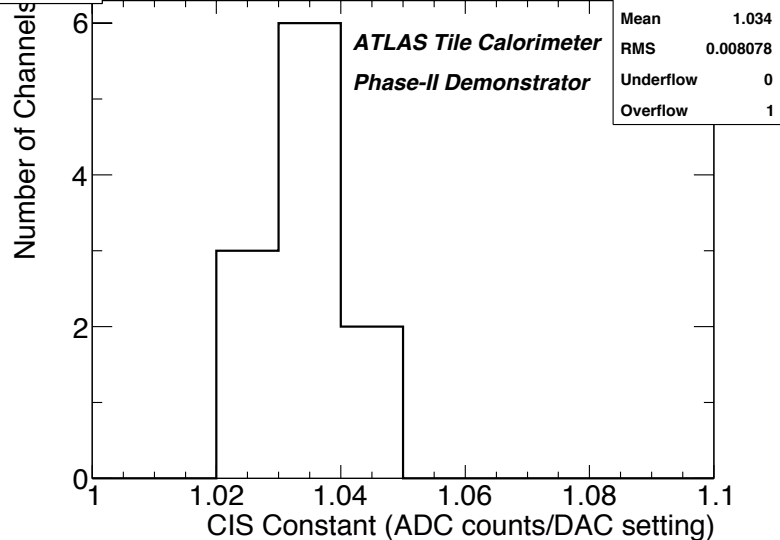
reconstructed Amplitude



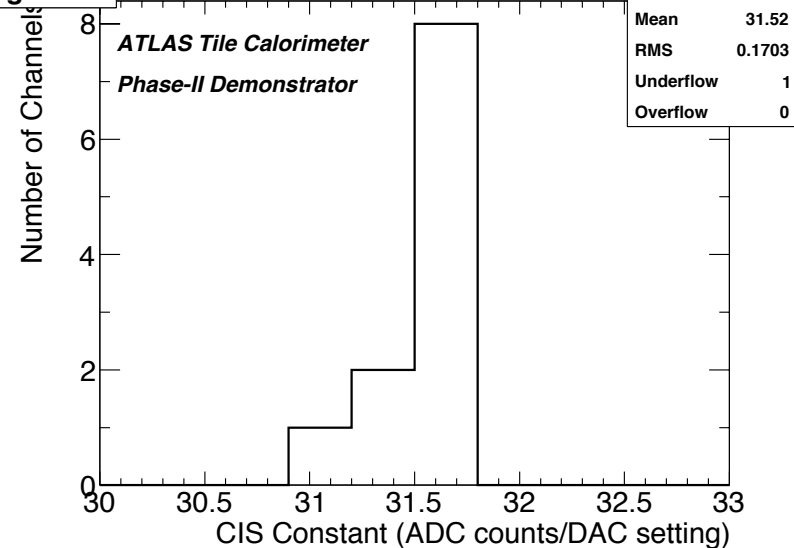
reconstructed Amplitude



Low Gain



High Gain

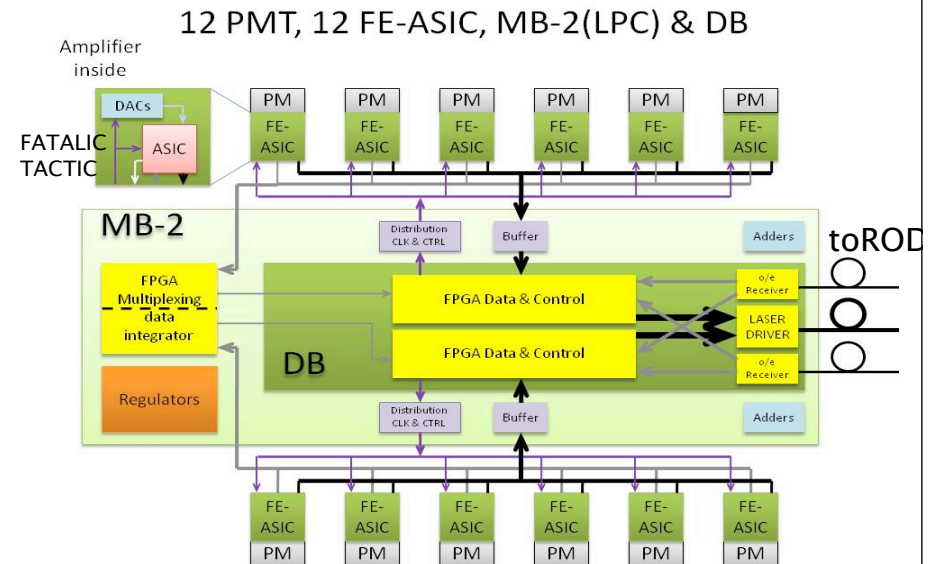
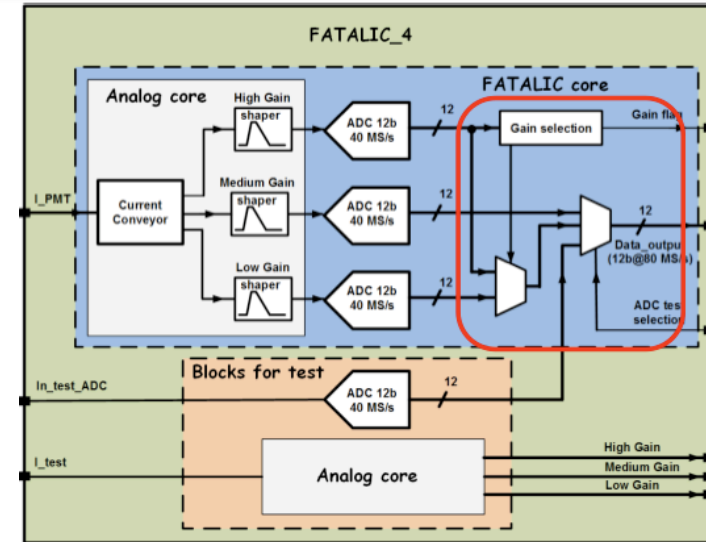




PMT read-out. Option 2 - FE-ASIC



- ☒ Based on the FATALIC chip family + TACTIC ADC
- ☒ IBM 130 nm technology. Shaping, 3 gain ranges (1, 8, 64)
- ☒ First prototypes (FATALIC 1/2) tested
 - ☒ Linearity and signal symmetry problems- under evaluation
- ☒ Version FATALIC 3 tested.
 - ☒ Circuit corrections + integrator amplifier
 - ☒ Reduced parasitic self effects
- ☒ New version FATALIC 4 foreseen very soon.





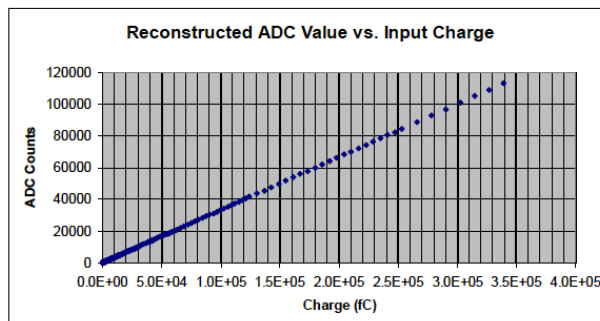
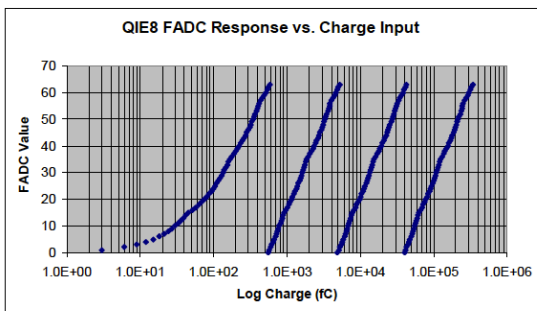
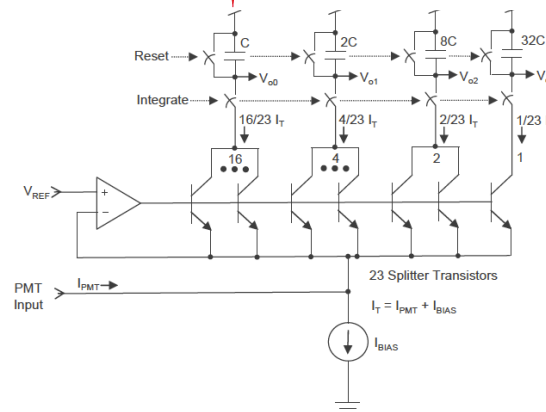
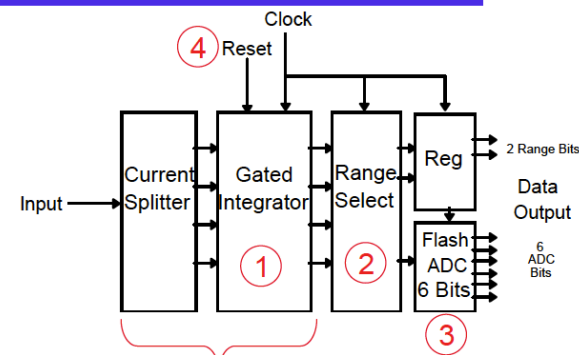
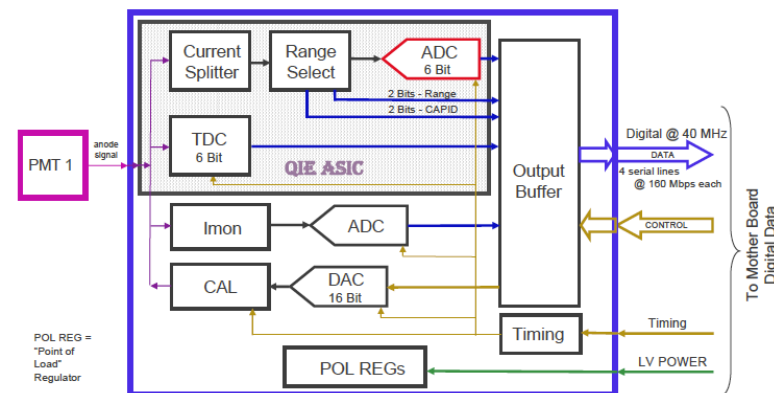
PMT read-out. Option 3 – QIE ASIC



Introduction:

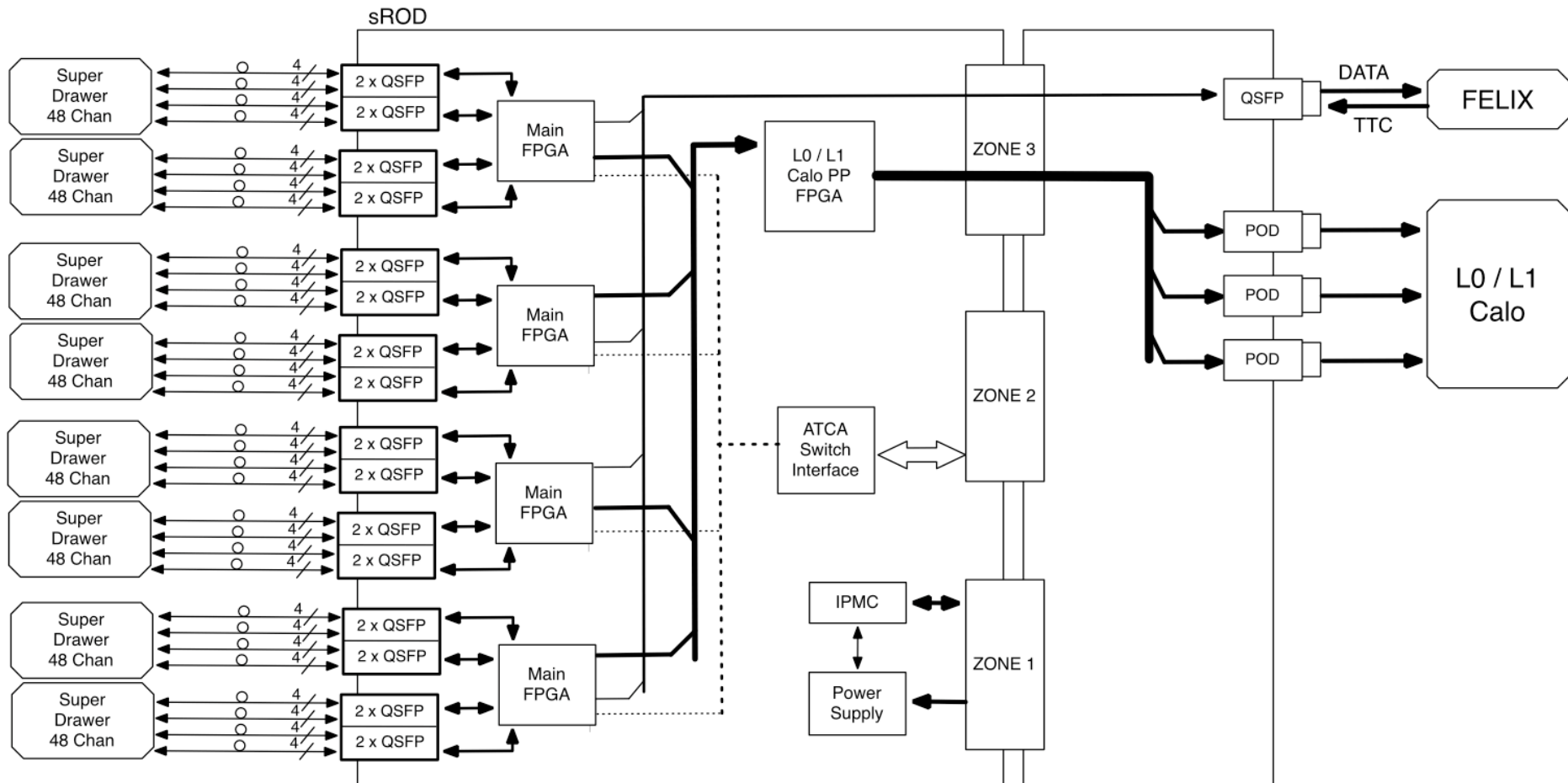
- ☒ Different concept – charge integrator
- ☒ 4 clock cycles to acquire the data
- ☒ Data Output : 10 bits encodes a 17-bit dynamic range
 - ☒ 6-bit ADC value, 2 bits range (4 ranges), 2 bits CAPID
- ☒ Good progress on 1st chip;
 - ☒ Problems identified, understood and were fixed in QIE10.3b
- ☒ Version 10.4. Target submission date: Nov., 2012.
 - ☒ Will be fully-functional, including data drivers and TDC
 - ☒ Availability: needed by CMS for 2015 installation.
 - ☒ Should be significant numbers of chips for testing
 - ☒ Possibility to piggy-back on CMS production
- ☒ PLANS:
 - ☒ First tests with QIE at CERN lab in late summer, 2013
 - ☒ Beam tests at CERN in 2015; Maybe at FNAL in 2014

A Conceptual Design of the QIE Front End Board





Possible layout for sROD





Readout dataflow in Phase-II

